



Material Composition Declaration

EPC2901C_55

Company Name	Efficient Power Conversion (EPC)	Issue Date:	4/24/2024
Contact Name:	Yanping Ma	Contact Title:	VP Quality
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Part Weight:	12.7 mg	Type of Product:	eGaN FET

Construction Element	Substance	CAS No. If Applicable	Weight	Mass	Sum	Mass
			(mg)	(%)	(%)	(ppm)
Chip	Silicon	7440-21-3	10.5319	83.1296	85.2349	831296
	Silicon oxide	7631-86-9	0.0361	0.2849		2849
	Silicon nitride	12033-89-5	0.0125	0.0989		989
	Gallium nitride	25617-97-4	0.0485	0.3829		3829
	Aluminum	7429-90-5	0.0834	0.6582		6582
	Aluminum nitride	24304-00-5	0.0103	0.0815		815
	Titanium	7440-32-6	0.0023	0.0178		178
	Titanium nitride	25583-20-4	0.0092	0.0725		725
	Copper	7440-50-8	0.0014	0.0110		110
	Tungsten	7440-33-7	0.0018	0.0142		142
	Polyimide		0.0613	0.4835	4835	
Under Bump Metal	Titanium	7440-32-6	0.0024	0.0187	0.0929	187
	Copper	7440-50-8	0.0094	0.0743		743
Solder Bump	Copper	7440-50-8	0.1176	0.9283	14.6722	9283
	Nickel	7440-02-0	0.0702	0.5537		5537
	Lead	7439-92-1	1.5875	12.5307		125307
	Tin	7440-31-5	0.0836	0.6595		6595
Sum in total:			12.6693	100.0000	100.0000	1000000

Note:

The substance content disclosed herewith is approximate and is based on engineering calculation. Statements are based on our present knowledge and may subject to change at any time due to technical requirements and development. EPC may update this document without notification. Statement may not include information regarding the minute quantities of dopant and metal materials in the electrical devices contained within the finished product.